

**LXR30M**
**FEATURES**

- \* Halogen-free type
- \* Glass passivated chip junctions
- \* Compliance to RoHS product
- \* Leadless chip form, no lead damage
- \* Low power loss, High efficiency
- \* High current capability

**APPLICATION**

- \* AC/DC Power Supply
- \* Communication Equipment

**MECHANICAL DATA**

**Case** : Packed with FRP substrate and epoxy underfilled

**Terminals** : Pure Tin plated (Lead-Free),  
solderable per MIL-STD-750, Method 2026.

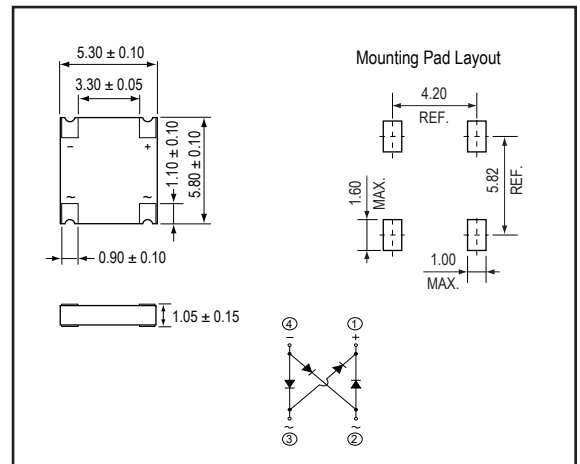
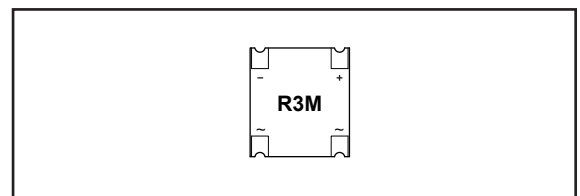
**Polarity** : Laser marking symbols

**PACKING**

- \* **5,000 pieces** per 13" (330mm ± 2mm) reel
- \* **2 reels** per box
- \* **5 boxes** per carton

**OUTLINE DIMENSIONS**
**Case : Z4PAK**

Unit : mm


**MARKING**

**Absolute Maximum Ratings (Ta = 25°C)**

ITEM	Symbol	Conditions	Rating	Unit
Repetitive peak reverse voltage	VRRM		1000	V
Average forward current	IF(AV)		3	A
Peak forward surge current	IFSM	8.3ms single half sine-wave	60	A
Reverse recovery time	Trr	IF = 0.5A, IR = 1.0A, Irr = 0.25A	500	nS
Operating junction and storage temperature Range	Tj, TSTG		-55 to +150	°C

**Electrical characteristics (Ta = 25°C)**

ITEM	Symbol	Conditions	Typ.	Max.	Unit
Forward voltage	VF	@ IF = 3A Ta = 25°C	1.10	1.30	V
Repetitive peak reverse current	Irrm	VR = Max. VRRM Ta = 25°C	0.20	5	uA
Current squared time	I <sup>2</sup> t	t < 8.3ms, Ta = 25°C	14.9	-	A <sup>2</sup> s
Thermal resistance	Rth(JA)	Junction to ambient (NOTE)	95	-	°C/W
	Rth(JC)	Junction to case (NOTE)	15	-	

NOTES : (1) Thermal resistance, junction to ambient, measured on PC board with 50mm<sup>2</sup> (0.03mm thick) land areas.

FIG.1 - FORWARD CURRENT DERATING CURVE

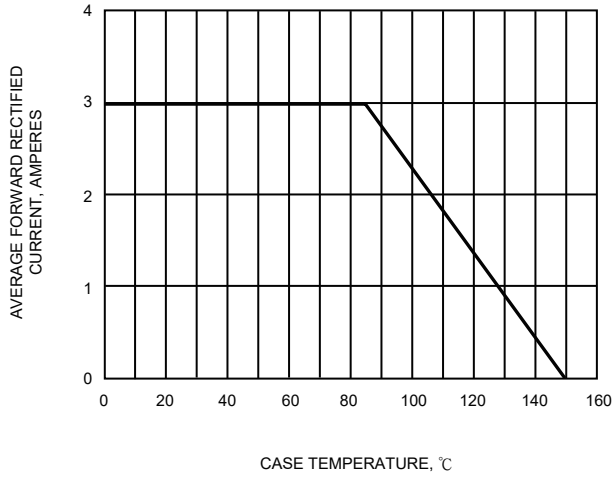


FIG.2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

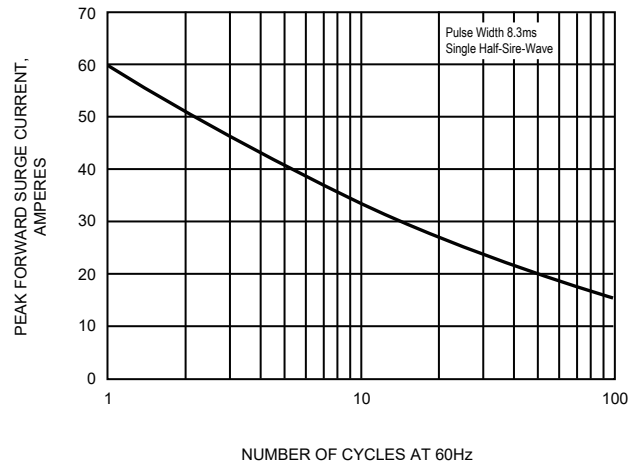


FIG.3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

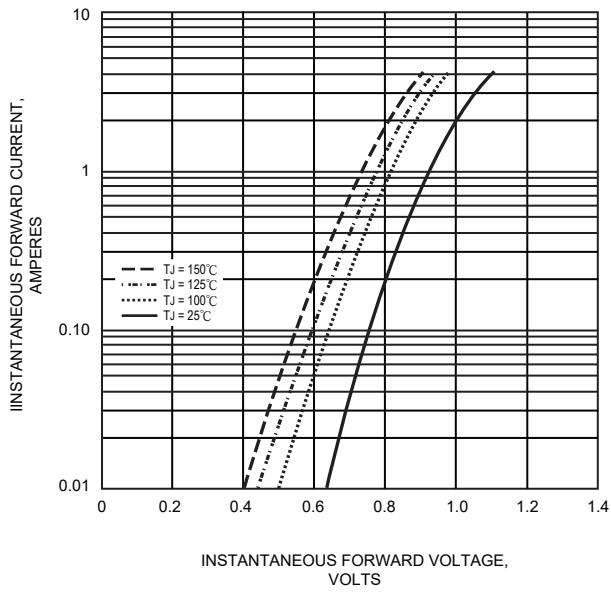


FIG.4 - TYPICAL REVERSE CHARACTERISTICS

